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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/730,335	12/04/2000	Charles H. Dennison	MI22-1577	8465

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WELLS ST. JOHN P.S.
601 W. FIRST AVENUE, SUITE 1300
SPOKANE, WA 99201

[REDACTED] EXAMINER

NADAV, ORI

[REDACTED] ART UNIT [REDACTED] PAPER NUMBER

2811

DATE MAILED: 10/01/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)
	09/730,335	DENNISON, CHARLES H. <i>HC</i>
Examiner	Art Unit	
ori nadav	2811	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) Responsive to communication(s) filed on 30 July 2003.
- 2a) This action is FINAL. 2b) This action is non-final.
- 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) Claim(s) 57-75 and 78-96 is/are pending in the application.
 - 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) Claim(s) 57-61 and 93 is/are allowed.
- 6) Claim(s) 62-75,78-92 and 94-96 is/are rejected.
- 7) Claim(s) _____ is/are objected to.
- 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) The specification is objected to by the Examiner.
- 10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- 11) The proposed drawing correction filed on 30 July 2003 is: a) approved b) disapproved by the Examiner.
 If approved, corrected drawings are required in reply to this Office action.
- 12) The oath or declaration is objected to by the Examiner.

Priority under 35 U.S.C. §§ 119 and 120

- 13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 - a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.
- 14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).
 - a) The translation of the foreign language provisional application has been received.
- 15) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

Attachment(s)

- 1) Notice of References Cited (PTO-892)
- 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s) 20.
- 4) Interview Summary (PTO-413) Paper No(s). _____.
- 5) Notice of Informal Patent Application (PTO-152)
- 6) Other: _____.

DETAILED ACTION

Drawings

The formal drawings were received on 7/30/2003. The examiner approves these drawings.

Claim Rejections - 35 USC § 112

The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

Claims 62-75, 78-92 and 94-96 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. The claimed limitations of a gate, a gate dielectric layer, source/drain regions and a channel region received within a common cross section of the substrate, as recited in claim 62 is unclear as to (a) what is received within the common cross-section, and (b) how a gate, a gate dielectric layer, source/drain regions and a channel region can be received within a cross-section, since a cross-section is just a representation of something that is cut at a right angle.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

1. Claims 62-64, 67-68, 70-71, 80-81, 85 and 89, insofar as in compliance with 35 U.S.C. 112, are rejected under 35 U.S.C. 103(a) as being unpatentable over Pfiester (4,997,785) in view of Wu (5,710,454), Hachiya (5,244,835) and Dennison (5,637,525).

Pfiester teaches in figure 7 and related text an Integrated circuitry comprising a substrate comprising a field effect transistor including a gate, a gate dielectric layer, source/drain regions 24, 26 and a channel region received within a common cross-section of the substrate; the gate comprising semiconductive material 16 conductively doped with a conductivity enhancing impurity of a first type N+ and a conductive diffusion barrier layer material 30 effective to restrict diffusion of first or second type conductivity enhancing impurity, wherein the semiconductive material within the insulating material within a common cross-section contacts the conductive diffusion barrier layer of the gate, and wherein the conductive diffusion barrier layer material is received over the gate semiconductive material, and the semiconductive material within the insulating material is received over the gate..

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Pfiester does not teach a contact structure extending through the insulative material to the gate within the common cross-section, wherein the contact structure including a semiconductive material provided through the insulative material being conductively doped with a conductivity enhancing impurity of a second type P+, such that the conductive diffusion barrier layer of the gate being provided between the gate semiconductive material and the semiconductive material provided through the insulative material. That is, Pfiester does not teach a contact structure including a semiconductive material provided through insulative material 44 or any insulative material surrounding the gate, being conductively doped with a conductivity enhancing impurity of a second type P+ and making contact to layer 20 having a conductivity enhancing impurity of a second type P+.

Wu teaches in figure 3 and related text a contact structure extending through insulative material 22a within a common cross-section to the gate, wherein the contact structure including a semiconductive material provided through the insulative material being conductively doped with a conductivity enhancing impurity of a conductivity type, such that the conductive diffusion barrier layer of the gate being provided between the gate semiconductive material and the semiconductive material provided through the insulative material, the insulative material comprises an opening substantially void of any conductive diffusion barrier layer material. wherein neither of the contact structure sidewalls aligning with either of the opposing sidewalls of the gate in one cross section (column 10, lines 51-58).

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Hachiya teaches in figure 4 a contact structure 16N including a semiconductive material being conductively doped with a conductivity enhancing impurity of a first N+ type making contact to a region of a semiconductive material being conductively doped with a conductivity enhancing impurity of a first N+ type, and a contact structure 17P including a semiconductive material being conductively doped with a conductivity enhancing impurity of a second P+ type making contact to a region of a semiconductive material being conductively doped with a conductivity enhancing impurity of a second P+ type.

Dennison teaches in figure 11 a contact structure 54 including a semiconductive material being conductively doped with a conductivity enhancing impurity of a first N+ type making contact to a region 56 of a semiconductive material being conductively doped with a conductivity enhancing impurity of a first N+ type, and a contact structure 40 including a semiconductive material being conductively doped with a conductivity enhancing impurity of a second P+ type making contact to a region 42 of a semiconductive material being conductively doped with a conductivity enhancing impurity of a second P+ type.

It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use a contact structure extending through the insulative material to the gate, wherein the contact structure including a semiconductive material provided through the insulative material within a common cross-section and being conductively doped with a conductivity enhancing impurity, as taught by Wu, of a second type P+, as taught by Hachiya and Dennison, such that the conductive diffusion barrier layer of the gate being provided between the gate

semiconductive material and the semiconductive material provided through the insulative material in Pfiester's device, in order to operate the device by providing external connections to the gate, and in order to simplify the processing steps of making the device and to reduce the contact resistance and the device characteristics, respectively. The combination is motivated by the teachings of Pfiester who points out that the device can be used in an application which requires a contact structure contacting the gate, and by the teachings of Hachiya and Dennison who point out the advantages of using a contact structure of one conductivity type to make contact to a region of the same conductivity type.

Regarding claim 64, it would have been obvious to a person of ordinary skill in the art at the time the invention was made to use a first type p and a second type n in Pfiester's device, in order to use the device in an application which requires electrical contact to the NMOS.

Regarding claim 68, the semiconductive material within the insulating material of prior art's device does not contact the conductive diffusion barrier layer of the gate.

Regarding claim 85, Pfiester teaches in figure 7 one gate electrode consists of a conductivity doped semiconductive material of the first type 16 and a conductive diffusion barrier layer 30.

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Regarding claim 89, Pfiester teaches in figure 7 a gate electrode can alternatively consist of a conductivity doped semiconductive material of the first type 16, a conductive diffusion barrier layer 30 and a conductive silicide 20.

2. Claims 65, 66, 69, 72, 74 and 78, insofar as in compliance with 35 U.S.C. 112, are rejected under 35 U.S.C. 103(a) as being unpatentable over Pfiester, Wu, Hachiya and Dennison, as applied to claim 62 above, and further in view of Ku (5,856,237).

Regarding claim 65, Pfiester, Wu, Hachiya and Dennison teach substantially the entire claimed structure, as applied to claim 62 above, except a gate also comprises a conductive silicide.

Ku teaches in figure 4F a gate comprises a conductive diffusion barrier layer 140 selected from the group consisting of WxNy, TiOxNy, and TiWxNy, and mixtures thereof over a conductive silicide 124 comprising TiSi.

It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use a gate also comprises a conductive silicide in prior art's device, in order to reduce the contact resistance of the gate.

Regarding claim 66, the silicide and the conductive diffusion barrier layer comprise the same material, Titanium.

3. Claim 73, insofar as in compliance with 35 U.S.C. 112, is rejected under 35 U.S.C. 103(a) as being unpatentable over Pfiester, Wu, Hachiya,

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Dennison and Ku, as applied to claim 72 above, and further in view of Chow et al. (4,847,111) and Charneski et al. (5,909,637)..

Pfiester, Wu, Hachiya, Dennison and Ku teach substantially the entire claimed structure, as applied to claim 72 above, except a conductive diffusion barrier layer comprising WxNy.

Chow et al. teach in figure 1c a conductive diffusion barrier layer comprising WxNy.

Charneski et al. teach a conductive diffusion barrier layer comprising WxNy, TiOxNy, TiN and TiWxNy (column 10, lines 20-22).

It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use a conductive diffusion barrier layer comprising WxNy in prior art's device, in order to prevent diffusion and to strengthen the adhesion, and because TiOxNy, TiN and WxNy are conventional interchangeable materials used as conductive barrier diffusion layers in a gate electrode. Note that substitution of materials is not patentable even when the substitution is new and useful. Safetran Systems Corp. v. Federal Sign & Signal Corp. (DC NIII, 1981) 215 USPQ 979.

4. Claim 75, insofar as in compliance with 35 U.S.C. 112, is rejected under 35 U.S.C. 103(a) as being unpatentable over Pfiester, Wu, Hachiya, Dennison and Ku, as applied to claim 72 above, and further in view of Igarashi and Charneski et al. (5,909,637)..

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Pfiester, Wu, Hachiya, Dennison and Ku teach substantially the entire claimed structure, as applied to claim 72 above, except a conductive diffusion barrier layer comprising TiWxNy.

Igarashi teaches a gate electrode comprising TiN or TiWxNy (column 4, lines 4-9).

Charneski et al. teach a conductive diffusion barrier layer comprising WxNy, TiOxNy, TiN and TiWxNy (column 10, lines 20-22).

It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use a conductive diffusion barrier layer comprising TiWxNy in prior art's device, in order to prevent diffusion and to strengthen the adhesion, and because TiOxNy, TiN and TiWxNy are conventional interchangeable materials used as conductive barrier diffusion layers in a gate electrode. Note that substitution of materials is not patentable even when the substitution is new and useful. *Safetran Systems Corp. v. Federal Sign & Signal Corp.* (DC NIII, 1981) 215 USPQ 979.

5. Claims 65 and 79, insofar as in compliance with 35 U.S.C. 112, are rejected under 35 U.S.C. 103(a) as being unpatentable over Pfiester, Wu, Hachiya and Dennison, as applied to claim 62 above, and further in view of Bai et al. (5,818,092).

Pfiester, Wu, Hachiya and Dennison teach substantially the entire claimed structure, as applied to claim 62 above, except a gate also comprises a conductive silicide over a conductive diffusion barrier layer.

Bai et al. teach in figure 2C a conductive silicide 220 over a conductive diffusion barrier layer 206.

It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use a gate also comprises a conductive silicide over a conductive diffusion barrier layer in prior art's device, in order to reduce the contact resistance of the gate.

Allowable Subject Matter

6. Claims 57-61 and 93 are allowed.
7. Claims 82-84, 86-88, 90-92 and 94-96 would be allowable if rewritten to overcome the rejection(s) under 35 U.S.C. 112, second paragraph, set forth in this Office action and to include all of the limitations of the base claim and any intervening claims.

Reasons for allowance

8. The following is an examiner's statement of reasons for allowance:
Prior art does not teach a conductive diffusion barrier layer comprising WxNy and TiWxNy, and a conductive diffusion barrier layer comprising TiOxNy and TiWxNy

Response to Arguments.

Applicant argues that the rejection to claim 62 has been overcome by the amendment to claim 62.

Amended claim 62 recites a gate, a gate dielectric layer, source/drain regions and a channel region received within a common cross section of the substrate. It is unclear as to (a) what is received within the common cross-section, and (b) how a gate, a gate dielectric layer, source/drain regions and a channel region can be received within a cross-section, since a cross-section is just a representation of a something that is cut at a right angle.

Papers related to this application may be submitted to Technology center (TC) 2800 by facsimile transmission. Papers should be faxed to TC 2800 via the TC 2800 Fax center located in Crystal Plaza 4, room 4-C23. The faxing of such papers must conform to the notice published in the Official Gazette, 1096 OG 30 (November 15, 1989). The Group 2811 Fax Center number is (703) 308-7722 and 308-7724. The Group 2811 Fax Center is to be used only for papers related to Group 2811 applications.

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Any inquiry concerning this communication or any earlier communication from the Examiner should be directed to *Examiner Nadav* whose telephone number is **(703) 308-8138**. The Examiner is in the Office generally between the hours of 7 AM to 4 PM (Eastern Standard Time) Monday through Friday. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas, can be reached at **(703) 308-2772**.

Any inquiry of a general nature or relating to the status of this application should be directed to the **Technology Center Receptionists** whose telephone number is **308-0956**



O.N.
September 27, 2003

ORI NADAV
PATENT EXAMINER
TECHNOLOGY CENTER 2800